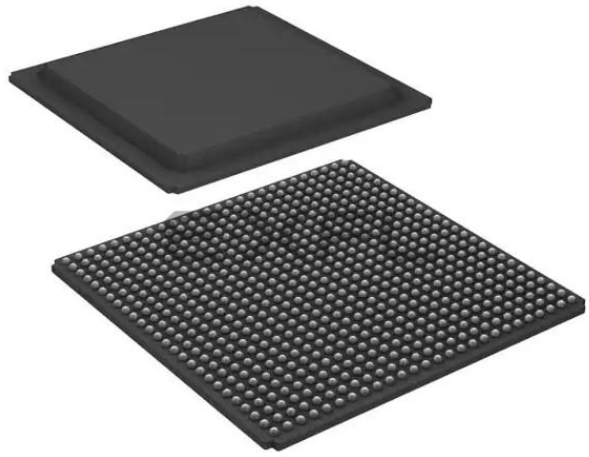
AMD Xilinx - XC3SD1800A-4FG676I Datasheet



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The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	4160
Number of Logic Elements/Cells	37440
Total RAM Bits	1548288
Number of I/O	519
Number of Gates	1800000
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	676-BGA
Supplier Device Package	676-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc3sd1800a-4fg676i

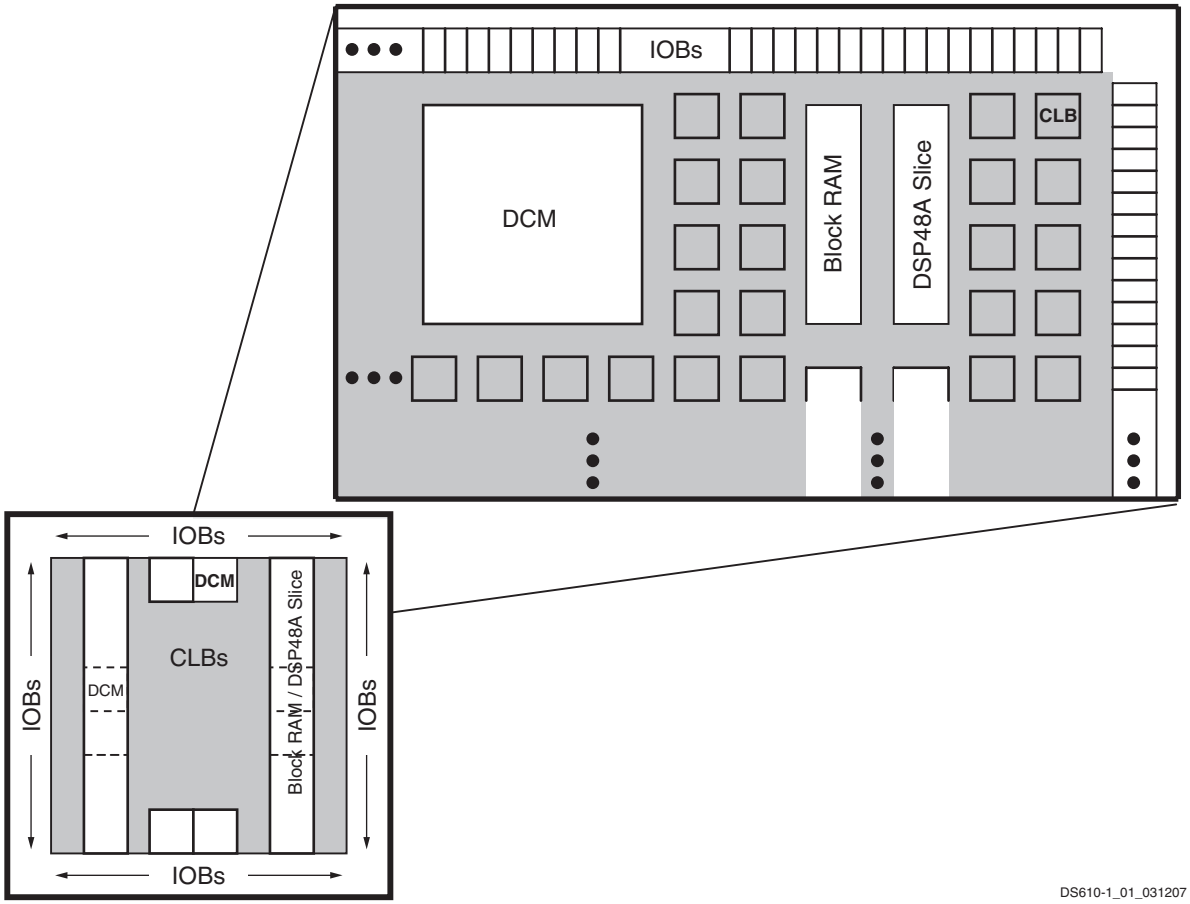
Architectural Overview

The Spartan-3A DSP family architecture consists of five fundamental programmable functional elements:

- **XtremeDSP™ DSP48A Slice** provides an 18-bit x 18-bit multiplier, 18-bit pre-adder, 48-bit post-adder/accumulator, and cascade capabilities for various DSP applications.
- **Block RAM** provides data storage in the form of 18-Kbit dual-port blocks.
- **Configurable Logic Blocks (CLBs)** contain flexible Look-Up Tables (LUTs) that implement logic plus storage elements used as flip-flops or latches. CLBs perform a wide variety of logical functions as well as store data.
- **Input/Output Blocks (IOBs)** control the flow of data between the I/O pins and the internal logic of the device. IOBs support bidirectional data flow plus 3-state operation. Supports a variety of signal standards, including several high-performance differential standards. Double Data-Rate (DDR) registers are included.
- **Digital Clock Manager (DCM) Blocks** provide self-calibrating, fully digital solutions for distributing, delaying, multiplying, dividing, and phase-shifting clock signals.

These elements are organized as shown in Figure 1. A dual ring of staggered IOBs surrounds a regular array of CLBs. The XC3SD1800A has four columns of DSP48As, and the XC3SD3400A has five columns of DSP48As. Each DSP48A has an associated block RAM. The DCMs are positioned in the center with two at the top and two at the bottom of the device and in the two outer columns of the 4 or 5 columns of block RAM and DSP48As.

The Spartan-3A DSP family features a rich network of routing that interconnect all five functional elements, transmitting signals among them. Each functional element has an associated switch matrix that permits multiple connections to the routing.



Notes:

1. The XC3SD1800A and XC3SD3400A have two DCMs on both the left and right sides, as well as the two DCMs at the top and bottom of the devices. The two DCMs on the left and right of the chips are in the middle of the outer Block RAM/DSP48A columns of the 4 or 5 columns in the selected device, as shown in the diagram above.
2. A detailed diagram of the DSP48A can be found in UG431: *XtremeDSP DSP48A for Spartan-3A DSP FPGAs User Guide.*

Figure 1: **Spartan-3A DSP Family Architecture**

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
04/02/07	1.0	Initial Xilinx release.
05/25/07	1.0.1	Minor edits.
06/18/07	1.2	Updated for Production release.
07/16/07	2.0	Added Low-power options.
06/02/08	2.1	Added reference to SCD 4103 for 750 Mbps performance. Add dual mark clarification to Package Marking. Updated links.
03/11/09	2.2	Simplified ordering information. Removed reference to SCD 4103.
10/04/10	3.0	Updated the Notice of Disclaimer section.

Notice of Disclaimer

General Recommended Operating Conditions

Table 7: **General Recommended Operating Conditions**

Symbol	Description			Min	Nominal	Max	Units
T_J	Junction temperature	Commercial		0	–	85	°C
		Industrial		–40	–	100	°C
V_{CCINT}	Internal supply voltage			1.14	1.20	1.26	V
V_{CCO} (1)	Output driver supply voltage			1.10	–	3.60	V
V_{CCAUX}	Auxiliary supply voltage (2)	V_{CCAUX} = 2.5		2.25	2.50	2.75	V
		V_{CCAUX} = 3.3		3.00	3.30	3.60	V
V_{IN} (3)	Input voltage	PCI™ IOSTANDARD		–0.5	–	V_{CCO}+0.5	V
		All other IOSTANDARDs	IP or IO_#	–0.5	–	4.10	V
			IO_Lxxy_# (4)	–0.5	–	4.10	V
T_{IN}	Input signal transition time (5)			–	–	500	ns

Notes:

1. This V_{CCO} range spans the lowest and highest operating voltages for all supported I/O standards. Table 10 lists the recommended V_{CCO} range specific to each of the single-ended I/O standards, and Table 12 lists that specific to the differential standards.
2. Define V_{CCAUX} selection using CONFIG VCCAUX constraint.
3. See XAPP459, *Eliminating I/O Coupling Effects when Interfacing Large-Swing Single-Ended Signals to User I/O Pins on Spartan-3 Families*.
4. For single-ended signals that are placed on a differential-capable I/O, V_{IN} of –0.2V to –0.5V is supported but can cause increased leakage between the two pins. See *Parasitic Leakage* in UG331, *Spartan-3 Generation FPGA User Guide*.
5. Measured between 10% and 90% V_{CCO}. Follow Signal Integrity recommendations.

Single-Ended I/O Standards

Table 10: **Recommended Operating Conditions for User I/Os Using Single-Ended Standards**

IOSTANDARD Attribute	V_{CCO} for Drivers[2]			V_{REF}			V_{IL}	V_{IH}[3]
	Min (V)	Nom (V)	Max (V)	Min (V)	Nom (V)	Max (V)	Max (V)	Min (V)
LVTTL	3.0	3.3	3.6	V_{REF} is not used for these I/O standards			0.8	2.0
LVCMOS33[4]	3.0	3.3	3.6				0.8	2.0
LVCMOS25[4,5]	2.3	2.5	2.7				0.7	1.7
LVCMOS18	1.65	1.8	1.95				0.4	0.8
LVCMOS15	1.4	1.5	1.6				0.4	0.8
LVCMOS12	1.1	1.2	1.3				0.4	0.7
PCI33_3[6]	3.0	3.3	3.6				0.3 • V_{CCO}	0.5 • V_{CCO}
PCI66_3[6]	3.0	3.3	3.6				0.3 • V_{CCO}	0.5 • V_{CCO}
HSTL_I	1.4	1.5	1.6	0.68	0.75	0.9	V_{REF} – 0.1	V_{REF} + 0.1
HSTL_III	1.4	1.5	1.6	–	0.9	–	V_{REF} – 0.1	V_{REF} + 0.1
HSTL_I_18	1.7	1.8	1.9	0.8	0.9	1.1	V_{REF} – 0.1	V_{REF} + 0.1
HSTL_II_18	1.7	1.8	1.9	–	0.9	–	V_{REF} – 0.1	V_{REF} + 0.1
HSTL_III_18	1.7	1.8	1.9	–	1.1	–	V_{REF} – 0.1	V_{REF} + 0.1
SSTL18_I	1.7	1.8	1.9	0.833	0.900	0.969	V_{REF} – 0.125	V_{REF} + 0.125
SSTL18_II	1.7	1.8	1.9	0.833	0.900	0.969	V_{REF} – 0.125	V_{REF} + 0.125
SSTL2_I	2.3	2.5	2.7	1.13	1.25	1.38	V_{REF} – 0.150	V_{REF} + 0.150
SSTL2_II	2.3	2.5	2.7	1.13	1.25	1.38	V_{REF} – 0.150	V_{REF} + 0.150
SSTL3_I	3.0	3.3	3.6	1.3	1.5	1.7	V_{REF} – 0.2	V_{REF} + 0.2
SSTL3_II	3.0	3.3	3.6	1.3	1.5	1.7	V_{REF} – 0.2	V_{REF} + 0.2

Notes:

1. Descriptions of the symbols used in this table are as follows:
   V_{CCO}—the supply voltage for output drivers
   V_{REF}—the reference voltage for setting the input switching threshold
   V_{IL}—the input voltage that indicates a Low logic level
   V_{IH}—the input voltage that indicates a High logic level
2. In general, the V_{CCO} rails supply only output drivers, not input circuits. The exceptions are for LVCMOS25 inputs when V_{CCAUX} = 3.3V range and for PCI I/O standards.
3. For device operation, the maximum signal voltage (V_{IH} max) can be as high as V_{IN} max. See Table 7.
4. There is approximately 100 mV of hysteresis on inputs using LVCMOS33 and LVCMOS25 I/O standards.
5. All Dedicated pins (PROG_B, DONE, SUSPEND, TCK, TDI, TDO, and TMS) draw power from the V_{CCAUX} rail and use the LVCMOS25 or LVCMOS33 standard depending on V_{CCAUX}. The Dual-Purpose configuration pins use the LVCMOS standard before the User mode. When using these pins as part of a standard 2.5V configuration interface, apply 2.5V to the V_{CCO} lines of Banks 0, 1, and 2 at power-on as well as throughout configuration.
6. For information on PCI IP solutions, see www.xilinx.com/pci. The PCI IOSTANDARD is not supported on input-only pins. The PCIX IOSTANDARD is available and has equivalent characteristics but no PCI-X IP is supported.

Pin-to-Pin Setup and Hold Times

Table 18: **Pin-to-Pin Setup and Hold Times for the IOB Input Path (System Synchronous)**

Symbol	Description	Conditions	Device	Speed Grade		Units
				-5	-4	
				Max	Max	
Setup Times						
T_{PSDCM}	When writing to the Input Flip-Flop (IFF), the time from the setup of data at the Input pin to the active transition at a Global Clock pin. The DCM is in use. No Input Delay is programmed.	LVCMOS25(2), IFD_DELAY_VALUE = 0, with DCM(4)	XC3SD1800A	2.65	3.11	ns
			XC3SD3400A	2.25	2.49	ns
T_{PSFD}	When writing to IFF, the time from the setup of data at the Input pin to an active transition at the Global Clock pin. The DCM is not in use. The Input Delay is programmed.	LVCMOS25(2), IFD_DELAY_VALUE = 6, without DCM	XC3SD1800A	2.98	3.39	ns
			XC3SD3400A	2.78	3.08	ns
Hold Times						
T_{PHDCM}	When writing to IFF, the time from the active transition at the Global Clock pin to the point when data must be held at the Input pin. The DCM is in use. No Input Delay is programmed.	LVCMOS25(3), IFD_DELAY_VALUE = 0, with DCM(4)	XC3SD1800A	–0.38	–0.38	ns
			XC3SD3400A	–0.26	–0.26	ns
T_{PHFD}	When writing to IFF, the time from the active transition at the Global Clock pin to the point when data must be held at the Input pin. The DCM is not in use. The Input Delay is programmed.	LVCMOS25(3), IFD_DELAY_VALUE = 6, without DCM	XC3SD1800A	–0.71	–0.71	ns
			XC3SD3400A	–0.65	–0.65	ns

Notes:

1. The numbers in this table are tested using the methodology presented in Table 26 and are based on the operating conditions set forth in Table 7 and Table 10.
2. This setup time requires adjustment whenever a signal standard other than LVCMOS25 is assigned to the Global Clock Input or the data Input. If this is true of the Global Clock Input, subtract the appropriate adjustment from Table 22. If this is true of the data Input, add the appropriate Input adjustment from the same table.
3. This hold time requires adjustment whenever a signal standard other than LVCMOS25 is assigned to the Global Clock Input or the data Input. If this is true of the Global Clock Input, add the appropriate Input adjustment from Table 22. If this is true of the data Input, subtract the appropriate Input adjustment from the same table. When the hold time is negative, it is possible to change the data before the clock's active edge.
4. DCM output jitter is included in all measurements.

Input Setup and Hold Times

Table 19: **Setup and Hold Times for the IOB Input Path**

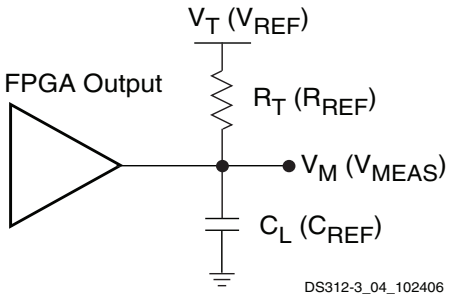
Symbol	Description	Conditions	DELAY_ VALUE	Device	Speed		Units
					-5	-4	
					Min	Min	
Setup Times							
T_{IOPICK}	Time from the setup of data at the Input pin to the active transition at the ICLK input of the Input Flip-Flop (IFF). No Input Delay is programmed.	LVCMOS25(2)	IFD_DELAY_VALUE=0	XC3SD1800A	1.65	1.81	ns
				XC3SD3400A	1.51	1.88	ns
$T_{IOPICKD}$	Time from the setup of data at the Input pin to the active transition at the ICLK input of the Input Flip-Flop (IFF). The Input Delay is programmed.	LVCMOS25(2)	1	XC3SD1800A	2.09	2.24	ns
			2		2.67	2.83	ns
			3		3.25	3.64	ns
			4		3.75	4.20	ns
			5		3.69	4.16	ns
			6		4.47	5.09	ns
			7		5.27	6.02	ns
			8		5.79	6.63	ns
			1	XC3SD3400A	2.07	2.44	ns
			2		2.57	3.02	ns
			3		3.44	3.81	ns
			4		4.01	4.39	ns
			5		3.89	4.26	ns
			6		4.43	5.08	ns
			7		5.20	5.95	ns
			8		5.70	6.55	ns
Hold Times							
T_{IOICKP}	Time from the active transition at the ICLK input of the Input Flip-Flop (IFF) to the point where data must be held at the Input pin. No Input Delay is programmed.	LVCMOS25(3)	0	XC3SD1800A	–0.63	–0.52	ns
				XC3SD3400A	–0.56	–0.56	ns

Timing Measurement Methodology

When measuring timing parameters at the programmable I/Os, different signal standards call for different test conditions. Table 26 lists the conditions to use for each standard.

The method for measuring Input timing is as follows: A signal that swings between a Low logic level of V_L and a High logic level of V_H is applied to the Input under test. Some standards also require the application of a bias voltage to the V_{REF} pins of a given bank to properly set the input-switching threshold. The measurement point of the Input signal (V_M) is commonly located halfway between V_L and V_H.

The Output test setup is shown in Figure 8. A termination voltage V_T is applied to the termination resistor R_T, the other end of which is connected to the Output. For each standard, R_T and V_T generally take on the standard values recommended for minimizing signal reflections. If the standard does not ordinarily use terminations (for example, LVCMOS, LVTTL), then R_T is set to 1MΩ to indicate an open connection, and V_T is set to zero. The same measurement point (V_M) that was used at the Input is also used at the Output.



Notes:

1. The names shown in parentheses are used in the IBIS file.

Figure 8: **Output Test Setup**

Table 26: **Test Methods for Timing Measurement at I/Os**

Signal Standard (IOSTANDARD)		Inputs			Outputs[2]		Inputs and Outputs
		V_{REF} (V)	V_L (V)	V_H (V)	R_T (Ω)	V_T (V)	V_M (V)
Single-Ended							
LVTTL		–	0	3.3	1M	0	1.4
LVCMOS33		–	0	3.3	1M	0	1.65
LVCMOS25		–	0	2.5	1M	0	1.25
LVCMOS18		–	0	1.8	1M	0	0.9
LVCMOS15		–	0	1.5	1M	0	0.75
LVCMOS12		–	0	1.2	1M	0	0.6
PCI33_3	Rising	–	Note 3	Note 3	25	0	0.94
	Falling				25	3.3	2.03
PCI66_3	Rising	–	Note 3	Note 3	25	0	0.94
	Falling				25	3.3	2.03
HSTL_I		0.75	V_{REF} – 0.5	V_{REF} + 0.5	50	0.75	V_{REF}
HSTL_III		0.9	V_{REF} – 0.5	V_{REF} + 0.5	50	1.5	V_{REF}
HSTL_I_18		0.9	V_{REF} – 0.5	V_{REF} + 0.5	50	0.9	V_{REF}
HSTL_II_18		0.9	V_{REF} – 0.5	V_{REF} + 0.5	25	0.9	V_{REF}
HSTL_III_18		1.1	V_{REF} – 0.5	V_{REF} + 0.5	50	1.8	V_{REF}
SSTL18_I		0.9	V_{REF} – 0.5	V_{REF} + 0.5	50	0.9	V_{REF}
SSTL18_II		0.9	V_{REF} – 0.5	V_{REF} + 0.5	25	0.9	V_{REF}
SSTL2_I		1.25	V_{REF} – 0.75	V_{REF} + 0.75	50	1.25	V_{REF}
SSTL2_II		1.25	V_{REF} – 0.75	V_{REF} + 0.75	25	1.25	V_{REF}
SSTL3_I		1.5	V_{REF} – 0.75	V_{REF} + 0.75	50	1.5	V_{REF}
SSTL3_II		1.5	V_{REF} – 0.75	V_{REF} + 0.75	25	1.5	V_{REF}

Table 26: **Test Methods for Timing Measurement at I/Os *(Cont'd)***

Signal Standard (IOSTANDARD)	Inputs			Outputs[2]		Inputs and Outputs
	V_{REF} (V)	V_L (V)	V_H (V)	R_T (Ω)	V_T (V)	V_M (V)
Differential						
LVDS_25	–	V_{ICM} – 0.125	V_{ICM} + 0.125	50	1.2	V_{ICM}
LVDS_33	–	V_{ICM} – 0.125	V_{ICM} + 0.125	50	1.2	V_{ICM}
BLVDS_25	–	V_{ICM} – 0.125	V_{ICM} + 0.125	1M	0	V_{ICM}
MINI_LVDS_25	–	V_{ICM} – 0.125	V_{ICM} + 0.125	50	1.2	V_{ICM}
MINI_LVDS_33	–	V_{ICM} – 0.125	V_{ICM} + 0.125	50	1.2	V_{ICM}
LVPECL_25	–	V_{ICM} – 0.3	V_{ICM} + 0.3	N/A	N/A	V_{ICM}
LVPECL_33	–	V_{ICM} – 0.3	V_{ICM} + 0.3	N/A	N/A	V_{ICM}
RSDS_25	–	V_{ICM} – 0.1	V_{ICM} + 0.1	50	1.2	V_{ICM}
RSDS_33	–	V_{ICM} – 0.1	V_{ICM} + 0.1	50	1.2	V_{ICM}
TMDS_33	–	V_{ICM} – 0.1	V_{ICM} + 0.1	50	3.3	V_{ICM}
PPDS_25	–	V_{ICM} – 0.1	V_{ICM} + 0.1	50	0.8	V_{ICM}
PPDS_33	–	V_{ICM} – 0.1	V_{ICM} + 0.1	50	0.8	V_{ICM}
DIFF_HSTL_I_18	–	V_{ICM} – 0.5	V_{ICM} + 0.5	50	0.9	V_{ICM}
DIFF_HSTL_II_18	–	V_{ICM} – 0.5	V_{ICM} + 0.5	50	0.9	V_{ICM}
DIFF_HSTL_III_18	–	V_{ICM} – 0.5	V_{ICM} + 0.5	50	1.8	V_{ICM}
DIFF_HSTL_I	–	V_{ICM} – 0.5	V_{ICM} + 0.5	50	0.9	V_{ICM}
DIFF_HSTL_III	–	V_{ICM} – 0.5	V_{ICM} + 0.5	50	0.9	V_{ICM}
DIFF_SSTL18_I	–	V_{ICM} – 0.5	V_{ICM} + 0.5	50	0.9	V_{ICM}
DIFF_SSTL18_II	–	V_{ICM} – 0.5	V_{ICM} + 0.5	50	0.9	V_{ICM}
DIFF_SSTL2_I	–	V_{ICM} – 0.5	V_{ICM} + 0.5	50	1.25	V_{ICM}
DIFF_SSTL2_II	–	V_{ICM} – 0.5	V_{ICM} + 0.5	50	1.25	V_{ICM}
DIFF_SSTL3_I	–	V_{ICM} – 0.5	V_{ICM} + 0.5	50	1.5	V_{ICM}
DIFF_SSTL3_II	–	V_{ICM} – 0.5	V_{ICM} + 0.5	50	1.5	V_{ICM}

Notes:

1. Descriptions of the relevant symbols are:
   V_{REF} – The reference voltage for setting the input switching threshold
   V_{ICM} – The common mode input voltage
   V_M – Voltage of measurement point on signal transition
   V_L – Low-level test voltage at Input pin
   V_H – High-level test voltage at Input pin
   R_T – Effective termination resistance, which takes on a value of 1 MΩ when no parallel termination is required
   V_T – Termination voltage
2. The load capacitance (C_L) at the Output pin is 0 pF for all signal standards.
3. According to the PCI specification. For information on PCI IP solutions, see www.xilinx.com/pci. The PCIX IOSTANDARD is available and has equivalent characteristics but no PCI-X IP is supported.

The capacitive load (C_L) is connected between the output and GND. *The Output timing for all standards, as published in the speed files and the data sheet, is always based on a C_L value of zero.* High-impedance probes (less than 1 pF) are used for all measurements. Any delay that the test fixture might contribute to test measurements is subtracted from those measurements to produce the final timing numbers as published in the speed files and data sheet.

Table 28: **Recommended Simultaneously Switching Outputs per V_{CCO}/GND Pair (V_{CCAUX} = 3.3V) *(Cont'd)***

Signal Standard (IOSTANDARD)			Package Type	
			CS484, FG676	
			Top, Bottom (Banks 0, 2)	Left, Right (Banks 1, 3)
LVCMOS25	Slow	2	76	76
		4	46	46
		6	33	33
		8	24	24
		12	18	18
		16	–	11
		24	–	7
	Fast	2	18	18
		4	14	14
		6	6	6
		8	6	6
		12	3	3
		16	–	3
		24	–	2
	QuietIO	2	76	76
		4	60	60
		6	48	48
		8	36	36
		12	36	36
		16	–	36
		24	–	8

Table 28: **Recommended Simultaneously Switching Outputs per V_{CCO}/GND Pair (V_{CCAUX} = 3.3V) *(Cont'd)***

Signal Standard (IOSTANDARD)			Package Type	
			CS484, FG676	
			Top, Bottom (Banks 0, 2)	Left, Right (Banks 1, 3)
LVCMOS18	Slow	2	64	64
		4	34	34
		6	22	22
		8	18	18
		12	–	13
		16	–	10
	Fast	2	18	18
		4	9	9
		6	7	7
		8	4	4
		12	–	4
		16	–	3
	QuietIO	2	64	64
		4	64	64
		6	48	48
		8	36	36
		12	–	36
		16	–	24
LVCMOS15	Slow	2	55	55
		4	31	31
		6	18	18
		8	–	15
		12	–	10
	Fast	2	25	25
		4	10	10
		6	6	6
		8	–	4
		12	–	3
	QuietIO	2	70	70
		4	40	40
		6	31	31
		8	–	31
		12	–	20

DSP48A Timing

To reference the DSP48A block diagram, see UG431: *XtremeDSP DSP48A for Spartan-3A DSP FPGA User Guide*.

Table 34: **Setup Times for the DSP48A**

Symbol	Description	Pre-adder	Multiplier	Post-adder	Speed Grade		Units
					-5	-4	
					Min	Min	
Setup Times of Data/Control Pins to the Input Register Clock							
T_{DSPDCK_AA}	A input to A register CLK	–	–	–	0.04	0.04	ns
T_{DSPDCK_DB}	D input to B register CLK	Yes	–	–	1.64	1.88	ns
T_{DSPDCK_CC}	C input to C register CLK	–	–	–	0.05	0.05	ns
T_{DSPDCK_DD}	D input to D register CLK	–	–	–	0.04	0.04	ns
T_{DSPDCK_OPB}	OPMODE input to B register CLK	Yes	–	–	0.37	0.42	ns
T_{DSPDCK_OPOP}	OPMODE input to OPMODE register CLK	–	–	–	0.06	0.06	ns
Setup Times of Data Pins to the Pipeline Register Clock							
T_{DSPDCK_AM}	A input to M register CLK	–	Yes	–	3.30	3.79	ns
T_{DSPDCK_BM}	B input to M register CLK	Yes	Yes	–	4.33	4.97	ns
		No	Yes	–	3.30	3.79	ns
T_{DSPDCK_DM}	D input to M register CLK	Yes	Yes	–	4.41	5.06	ns
T_{DSPDCK_OPM}	OPMODE to M register CLK	Yes	Yes	–	4.72	5.42	ns
Setup Times of Data/Control Pins to the Output Register Clock							
T_{DSPDCK_AP}	A input to P register CLK	–	Yes	Yes	4.78	5.49	ns
T_{DSPDCK_BP}	B input to P register CLK	Yes	Yes	Yes	5.87	6.74	ns
		No	Yes	Yes	4.77	5.48	ns
T_{DSPDCK_DP}	D input to P register CLK	Yes	Yes	Yes	5.95	6.83	ns
T_{DSPDCK_CP}	C input to P register CLK	–	–	Yes	1.90	2.18	ns
T_{DSPDCK_OPP}	OPMODE input to P register CLK	Yes	Yes	Yes	6.25	7.18	ns

Notes:

1. "Yes" means that the component is in the path. "No" means that the component is being bypassed. "–" means that no path exists, so it is not applicable.
2. The numbers in this table are based on the operating conditions set forth in Table 7.

Phase Shifter (PS)

Table 40: **Recommended Operating Conditions for the PS in Variable Phase Mode**

Symbol	Description	Speed Grade				Units
		-5		-4		
		Min	Max	Min	Max	
Operating Frequency Ranges						
PSCLK_FREQ (FPSCLK)	Frequency for the PSCLK input	1	167	1	167	MHz
Input Pulse Requirements						
PSCLK_PULSE	PSCLK pulse width as a percentage of the PSCLK period	40%	60%	40%	60%	–

Table 41: **Switching Characteristics for the PS in Variable Phase Mode**

Symbol	Description		Phase Shift Amount	Units
Phase Shifting Range				
MAX_STEPS(2,3)	Maximum allowed number of DCM_DELAY_STEP steps for a given CLKIN clock period, where T = CLKIN clock period in ns. If using CLKIN_DIVIDE_BY_2 = TRUE, double the effective clock period.	CLKIN < 60 MHz	±[INTEGER(10 • (T_{CLKIN} – 3 ns))]	steps
		CLKIN ≥ 60 MHz	±[INTEGER(15 • (T_{CLKIN} – 3 ns))]	
FINE_SHIFT_RANGE_MIN	Minimum guaranteed delay for variable phase shifting		±[MAX_STEPS • DCM_DELAY_STEP_MIN]	ns
FINE_SHIFT_RANGE_MAX	Maximum guaranteed delay for variable phase shifting		±[MAX_STEPS • DCM_DELAY_STEP_MAX]	ns

Notes:

1. The numbers in this table are based on the operating conditions set forth in Table 7 and Table 40.
2. The maximum variable phase shift range, MAX_STEPS, is only valid when the DCM is has no initial fixed phase shifting, that is, the PHASE_SHIFT attribute is set to 0.
3. The DCM_DELAY_STEP values are provided at the bottom of Table 37.

Miscellaneous DCM Timing

Table 42: **Miscellaneous DCM Timing**

Symbol	Description	Min	Max	Units
DCM_RST_PW_MIN	Minimum duration of a RST pulse width	3	–	CLKIN cycles

Suspend Mode Timing

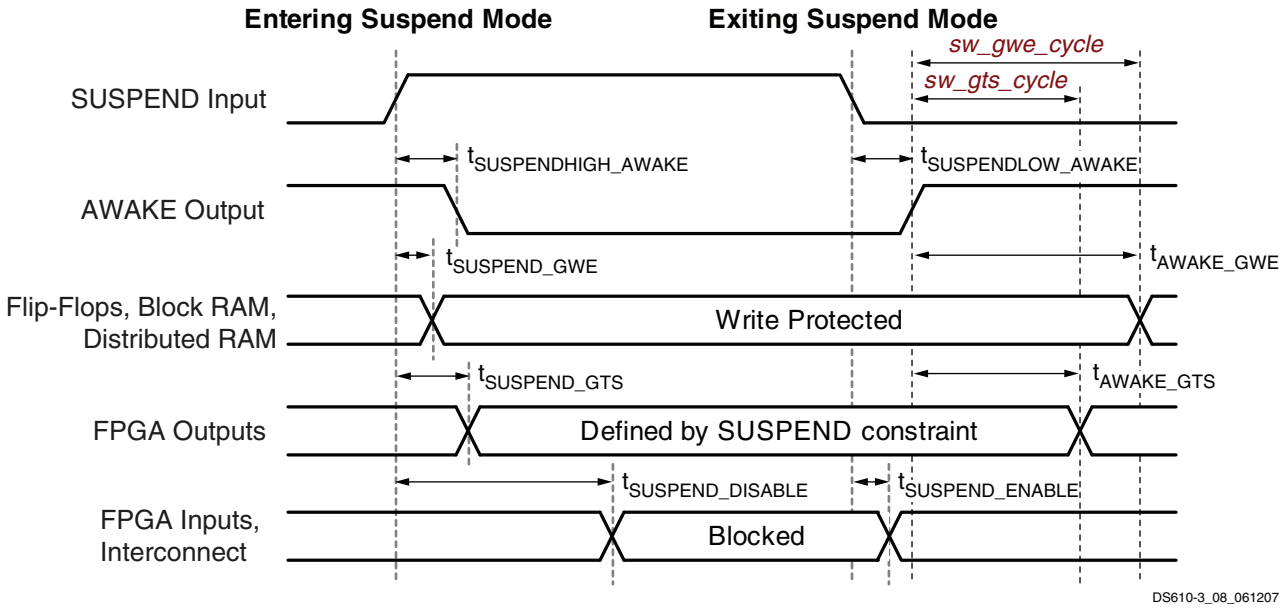


Figure 9: **Suspend Mode Timing**

Table 44: **Suspend Mode Timing Parameters**

Symbol	Description	Min	Typ	Max	Units
Entering Suspend Mode					
$T_{SUSPENDHIGH\_AWAKE}$	Rising edge of SUSPEND pin to falling edge of AWAKE pin without glitch filter (***suspend_filter:No***)	–	7	–	ns
$T_{SUSPENDFILTER}$	Adjustment to SUSPEND pin rising edge parameters when glitch filter enabled (***suspend_filter:Yes***)	+160	+300	+600	ns
$T_{SUSPEND\_GTS}$	Rising edge of SUSPEND pin until FPGA output pins drive their defined SUSPEND constraint behavior	–	10	–	ns
$T_{SUSPEND\_GWE}$	Rising edge of SUSPEND pin to write-protect lock on all writable clocked elements	–	<5	–	ns
$T_{SUSPEND\_DISABLE}$	Rising edge of the SUSPEND pin to FPGA input pins and interconnect disabled	–	340	–	ns
Exiting Suspend Mode					
$T_{SUSPENDLOW\_AWAKE}$	Falling edge of the SUSPEND pin to rising edge of the AWAKE pin. Does not include DCM lock time.	–	4 to 108	–	µs
$T_{SUSPEND\_ENABLE}$	Falling edge of the SUSPEND pin to FPGA input pins and interconnect re-enabled	–	3.7 to 109	–	µs
T_{AWAKE_GWE1}	Rising edge of the AWAKE pin until write-protect lock released on all writable clocked elements, using ***sw_clk:InternalClock*** and ***sw_gwe_cycle:1***.	–	67	–	ns
T_{AWAKE_GWE512}	Rising edge of the AWAKE pin until write-protect lock released on all writable clocked elements, using ***sw_clk:InternalClock*** and ***sw_gwe_cycle:512***.	–	14	–	µs
T_{AWAKE_GTS1}	Rising edge of the AWAKE pin until outputs return to the behavior described in the FPGA application, using ***sw_clk:InternalClock*** and ***sw_gts_cycle:1***.	–	57	–	ns
T_{AWAKE_GTS512}	Rising edge of the AWAKE pin until outputs return to the behavior described in the FPGA application, using ***sw_clk:InternalClock*** and ***sw_gts_cycle:512***.	–	14	–	µs

Notes:

1. These parameters based on characterization.
2. For information on using the Spartan-3A DSP Suspend feature, see XAPP480: *Using Suspend Mode in Spartan-3 Generation FPGAs*.

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
04/02/07	1.0	Initial Xilinx release.
05/25/07	1.0.1	Minor edits.
06/18/07	1.2	Updated for v1.29 production speed files. Noted banking rules in Table 11 and Table 12. Added DIFF_HSTL_I and DIFF_HSTL_III to Table 12, Table 13, and Table 26. Updated TMDS DC characteristics in Table 13. Updated I/O Test Method values in Table 26. Added Simultaneously Switching Output limits in Table 28. Updated DSP48A timing symbols, descriptions, and values in Table 34. Added power-on timing in Table 45. Added CCLK specifications for Commercial in Table 46 through Table 48. Updated Slave Parallel timing in Table 51. Updated JTAG specifications in Table 56.
07/16/07	2.0	Added Low-power options and updated typical values for quiescent current in Table 9. Updated DSP48A timing in Table 34 and Table 35.
06/02/08	2.1	Improved V_{CCAUXT} and V_{CCO2T} POR minimum in Table 4 and updated V_{CCO} POR levels in Figure 10. Added V_{IN} to Recommended Operating Conditions in Table 7 and added reference to XAPP459, "Eliminating I/O Coupling Effects when Interfacing Large-Swing Single-Ended Signals to User I/O Pins." Reduced typical I_{CCINTQ} and I_{CCAUXQ} quiescent current values by 20%-44% in Table 9. Increased V_{IL} max to 0.4V for LVCMOS12/15/18 and improved V_{IH} min to 0.7V for LVCMOS12 in Table 10. Changed V_{OL} max to 0.4V and V_{OH} min to V_{CCO}–0.4V for LVCMOS15/18 in Table 11. Added reference to V_{CCAUX} in Simultaneously Switching Output Guidelines. Removed DNA_RETENTION limit of 10 years in Table 14 since number of Read cycles is the only unique limit. Updated speed files to v1.31 in Table 16 and elsewhere. Updated IOB Setup and Hold times with device-specific values in Table 19. Added reference to Sample Window in Table 20. Updated IOB Propagation times with device-specific values in Table 21. Improved SSTL_18_II SSO value in Table 28. Improved F_{BUFG} for -4 to 334 MHz in Table 32. Added references to 375 MHz performance via SCD 4103 in Table 32,Table 37, Table 38, and Table 39. Added explanatory footnotes to DSP48A Timing tables. Simplified DSP48A F_{MAX} to value with all registers used in Table 35. Improved FBUFG in Table 32 for -4 speed grade. Updated CCLK output maximum period in Table 46 to match minimum frequency in Table 47. Replaced BPI with SPI specification descriptions in Table 52. Corrected BPI Figure 14 and Table 54 from falling edge to rising edge. Added references to Spartan-3 Generation User Guides. Updated links.
03/11/09	2.2	Changed typical quiescent current temperature from ambient to quiescent. Updated selected I/O standard DC characteristics. Removed PCIX IOSTANDARD due to limited PCIX interface support. Added T_{IOPI} and T_{IOPID} to Table 21. Updated BPI configuration waveforms in Figure 14 and updated Table 55. Removed references to SCD 4103.
10/04/10	3.0	Added I_{IK} to Table 3. Updated description for V_{IN} in Table 7 including adding note 4. Also, added note 2 to I_L in Table 8 to note potential leakage between pins of a differential pair. Added note 6 to Table 10. Updated notes 5 and 6 in Table 12. Corrected symbols for $T_{SUSPEND\_GTS}$ and $T_{SUSPEND\_GWE}$ in Table 44.

Table 66: **Spartan-3A DSP FG676 Pinout for XC3SD1800A FPGA *(Cont'd)***

Bank	XC3SD1800A Pin Name	FG676 Ball	Type
0	IP_0/VREF_0	D14	VREF
0	IO_L22P_0	D16	I/O
0	IO_L21P_0	D17	I/O
0	IO_L17P_0	D18	I/O
0	IO_L11P_0	D20	I/O
0	IO_L10N_0	D21	I/O
0	IO_L05P_0	D22	I/O
0	IO_L06P_0	D23	I/O
0	IO_L44P_0	C5	I/O
0	IO_L41N_0	C6	I/O
0	IO_L42N_0	C7	I/O
0	IO_L40P_0	C8	I/O
0	IO_L34P_0	C10	I/O
0	IO_L32P_0	C11	I/O
0	IO_L30N_0	C12	I/O
0	IO_L28N_0/GCLK11	C13	GCLK
0	IO_L22N_0	C15	I/O
0	IO_L21N_0	C16	I/O
0	IO_L19P_0	C17	I/O
0	IO_L17N_0	C18	I/O
0	IO_L11N_0	C20	I/O
0	IO_L09P_0	C21	I/O
0	IO_L05N_0	C22	I/O
0	IO_L06N_0	C23	I/O
0	IO_L51N_0	B3	I/O
0	IO_L45N_0	B4	I/O
0	IO_L41P_0	B6	I/O
0	IO_L42P_0	B7	I/O
0	IO_L38N_0	B8	I/O
0	IO_L36N_0	B9	I/O
0	IO_L33N_0	B10	I/O
0	IO_L29N_0	B12	I/O
0	IO_L28P_0/GCLK10	B13	GCLK
0	IO_L26P_0/GCLK6	B14	GCLK
0	IO_L23P_0	B15	I/O
0	IO_L19N_0	B17	I/O
0	IO_L18P_0	B18	I/O
0	IO_L15P_0	B19	I/O
0	IO_L14P_0/VREF_0	B20	VREF

Table 66: **Spartan-3A DSP FG676 Pinout for XC3SD1800A FPGA *(Cont'd)***

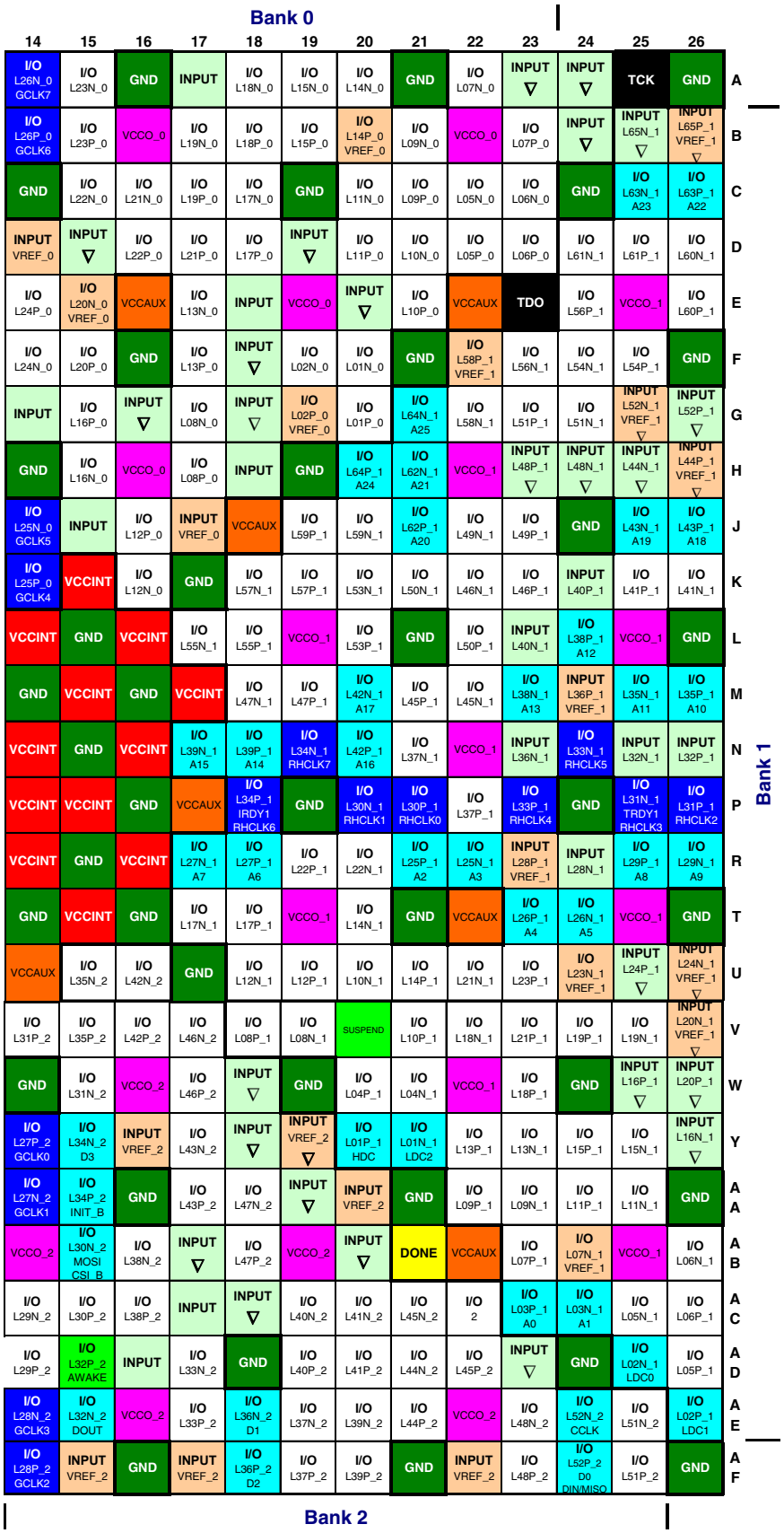
Bank	XC3SD1800A Pin Name	FG676 Ball	Type
0	IO_L09N_0	B21	I/O
0	IO_L07P_0	B23	I/O
0	IO_L51P_0	A3	I/O
0	IO_L45P_0	A4	I/O
0	IP_0	A7	INPUT
0	IO_L38P_0	A8	I/O
0	IO_L36P_0	A9	I/O
0	IO_L33P_0	A10	I/O
0	IO_L29P_0	A12	I/O
0	IP_0	A13	INPUT
0	IO_L26N_0/GCLK7	A14	GCLK
0	IO_L23N_0	A15	I/O
0	IP_0	A17	INPUT
0	IO_L18N_0	A18	I/O
0	IO_L15N_0	A19	I/O
0	IO_L14N_0	A20	I/O
0	IO_L07N_0	A22	I/O
0	IP_0	G16	INPUT
0	IP_0	E9	INPUT
0	IP_0	D15	INPUT
0	IP_0	D19	INPUT
0	IP_0	B24	INPUT
0	IP_0	A5	INPUT
0	IP_0	A23	INPUT
0	IP_0	F9	INPUT
0	IP_0	E20	INPUT
0	IP_0	A24	INPUT
0	IP_0	G18	INPUT
0	IP_0	F10	INPUT
0	IP_0	F18	INPUT
0	IP_0	E6	INPUT
0	IP_0	D5	INPUT
0	IP_0	C4	INPUT
0	VCCO_0	H11	VCCO
0	VCCO_0	H16	VCCO
0	VCCO_0	E8	VCCO
0	VCCO_0	E13	VCCO
0	VCCO_0	E19	VCCO
0	VCCO_0	B5	VCCO

Table 66: **Spartan-3A DSP FG676 Pinout for XC3SD1800A FPGA *(Cont'd)***

Bank	XC3SD1800A Pin Name	FG676 Ball	Type
2	IO_L41N_2	AC20	I/O
2	IO_L45N_2	AC21	I/O
2	IO_2	AC22	I/O
2	IP_2/VREF_2	AB6	VREF
2	IO_L14N_2	AB7	I/O
2	IO_L15P_2	AB9	I/O
2	IO_L21P_2	AB12	I/O
2	IP_2	AB13	INPUT
2	IO_L30N_2/MOSI/CSI_B	AB15	DUAL
2	IO_L38N_2	AB16	I/O
2	IO_L47P_2	AB18	I/O
2	IO_L02N_2/CSO_B	AA7	DUAL
2	IP_2/VREF_2	AA9	VREF
2	IO_L12N_2	AA10	I/O
2	IO_L17N_2/VS2	AA12	DUAL
2	IO_L25P_2/GCLK12	AA13	GCLK
2	IO_L27N_2/GCLK1	AA14	GCLK
2	IO_L34P_2/INIT_B	AA15	DUAL
2	IO_L43P_2	AA17	I/O
2	IO_L47N_2	AA18	I/O
2	IP_2/VREF_2	AA20	VREF
2	IP_2	AD5	INPUT
2	IP_2	AD23	INPUT
2	IP_2	AC5	INPUT
2	IP_2	AC7	INPUT
2	IP_2	AC18	INPUT
2	IP_2/VREF_2	AB10	VREF
2	IP_2	AB20	INPUT
2	IP_2	AA19	INPUT
2	IP_2	AF2	INPUT
2	IP_2	AB17	INPUT
2	IP_2	Y8	INPUT
2	IP_2	Y11	INPUT
2	IP_2	Y18	INPUT
2	IP_2/VREF_2	Y19	VREF
2	IP_2	W18	INPUT
2	IP_2	AA8	INPUT
2	VCCO_2	W11	VCCO
2	VCCO_2	W16	VCCO

Table 66: **Spartan-3A DSP FG676 Pinout for XC3SD1800A FPGA *(Cont'd)***

Bank	XC3SD1800A Pin Name	FG676 Ball	Type
2	VCCO_2	AE5	VCCO
2	VCCO_2	AE11	VCCO
2	VCCO_2	AE16	VCCO
2	VCCO_2	AE22	VCCO
2	VCCO_2	AB8	VCCO
2	VCCO_2	AB14	VCCO
2	VCCO_2	AB19	VCCO
3	IO_L53P_3	Y1	I/O
3	IO_L53N_3	Y2	I/O
3	IP_L54P_3	Y3	INPUT
3	IO_L57P_3	Y5	I/O
3	IO_L57N_3	Y6	I/O
3	IP_L50P_3	W1	INPUT
3	IP_L50N_3/VREF_3	W2	VREF
3	IO_L52P_3	W3	I/O
3	IO_L52N_3	W4	I/O
3	IO_L63N_3	W6	I/O
3	IO_L63P_3	W7	I/O
3	IO_L47P_3	V1	I/O
3	IO_L47N_3	V2	I/O
3	IP_L46N_3	V4	INPUT
3	IO_L49N_3	V5	I/O
3	IO_L59N_3	V6	I/O
3	IO_L59P_3	V7	I/O
3	IO_L61N_3	V8	I/O
3	IO_L44P_3	U1	I/O
3	IO_L44N_3	U2	I/O
3	IP_L46P_3	U3	INPUT
3	IO_L42N_3	U4	I/O
3	IO_L49P_3	U5	I/O
3	IO_L51N_3	U6	I/O
3	IO_L56P_3	U7	I/O
3	IO_L56N_3	U8	I/O
3	IO_L61P_3	U9	I/O
3	IO_L38P_3	T3	I/O
3	IO_L38N_3	T4	I/O
3	IO_L42P_3	T5	I/O
3	IO_L51P_3	T7	I/O
3	IO_L48N_3	T9	I/O



Right Half of FG676 Package (Top View)

Figure 17: FG676 Package Footprint for XC3SD1800A FPGA (Top View–Right Half)

Table 68: **Spartan-3A DSP FG676 Pinout for XC3SD3400A FPGA *(Cont'd)***

Bank	XC3SD3400A Pin Name	FG676 Ball	Type
GND	GND	P12	GND
GND	GND	P16	GND
GND	GND	P19	GND
GND	GND	P24	GND
GND	GND	N3	GND
GND	GND	N8	GND
GND	GND	N11	GND
GND	GND	N15	GND
GND	GND	M12	GND
GND	GND	M14	GND
GND	GND	M16	GND
GND	GND	L1	GND
GND	GND	L6	GND
GND	GND	L11	GND
GND	GND	L13	GND
GND	GND	L15	GND
GND	GND	L21	GND
GND	GND	L26	GND
GND	GND	K10	GND
GND	GND	K17	GND
GND	GND	J24	GND
GND	GND	H3	GND
GND	GND	H8	GND
GND	GND	H14	GND
GND	GND	H19	GND
GND	GND	G2	GND
GND	GND	G5	GND
GND	GND	G16	GND
GND	GND	F1	GND
GND	GND	F6	GND
GND	GND	F11	GND
GND	GND	F16	GND
GND	GND	F21	GND
GND	GND	F26	GND
GND	GND	E9	GND
GND	GND	D2	GND
GND	GND	D15	GND
GND	GND	D19	GND
GND	GND	C3	GND

Table 68: **Spartan-3A DSP FG676 Pinout for XC3SD3400A FPGA *(Cont'd)***

Bank	XC3SD3400A Pin Name	FG676 Ball	Type
GND	GND	C9	GND
GND	GND	C14	GND
GND	GND	C19	GND
GND	GND	C24	GND
GND	GND	B24	GND
GND	GND	B25	GND
GND	GND	AF1	GND
GND	GND	AF6	GND
GND	GND	AF11	GND
GND	GND	AF16	GND
GND	GND	AF21	GND
GND	GND	AF26	GND
GND	GND	AD3	GND
GND	GND	AD5	GND
GND	GND	AD8	GND
GND	GND	AD13	GND
GND	GND	AD18	GND
GND	GND	AD23	GND
GND	GND	AD24	GND
GND	GND	AC5	GND
GND	GND	AC7	GND
GND	GND	AC18	GND
GND	GND	AB3	GND
GND	GND	AB10	GND
GND	GND	AB20	GND
GND	GND	AA1	GND
GND	GND	AA4	GND
GND	GND	AA6	GND
GND	GND	AA11	GND
GND	GND	AA16	GND
GND	GND	AA19	GND
GND	GND	AA21	GND
GND	GND	AA26	GND
GND	GND	A1	GND
GND	GND	A5	GND
GND	GND	A6	GND
GND	GND	A11	GND
GND	GND	A16	GND
GND	GND	A21	GND

Table 68: **Spartan-3A DSP FG676 Pinout for XC3SD3400A FPGA *(Cont'd)***

Bank	XC3SD3400A Pin Name	FG676 Ball	Type
GND	GND	A23	GND
GND	GND	A26	GND
VCCAUX	SUSPEND	V20	PWRMGMT
VCCAUX	DONE	AB21	CONFIG
VCCAUX	PROG_B	A2	CONFIG
VCCAUX	TDI	G7	JTAG
VCCAUX	TDO	E23	JTAG
VCCAUX	TMS	D4	JTAG
VCCAUX	TCK	A25	JTAG
VCCAUX	VCCAUX	W26	VCCAUX
VCCAUX	VCCAUX	V9	VCCAUX
VCCAUX	VCCAUX	U14	VCCAUX
VCCAUX	VCCAUX	T22	VCCAUX
VCCAUX	VCCAUX	P17	VCCAUX
VCCAUX	VCCAUX	N10	VCCAUX
VCCAUX	VCCAUX	L5	VCCAUX
VCCAUX	VCCAUX	K13	VCCAUX
VCCAUX	VCCAUX	J18	VCCAUX
VCCAUX	VCCAUX	H23	VCCAUX
VCCAUX	VCCAUX	G26	VCCAUX
VCCAUX	VCCAUX	F9	VCCAUX
VCCAUX	VCCAUX	E5	VCCAUX
VCCAUX	VCCAUX	E16	VCCAUX
VCCAUX	VCCAUX	E20	VCCAUX
VCCAUX	VCCAUX	E22	VCCAUX
VCCAUX	VCCAUX	D1	VCCAUX
VCCAUX	VCCAUX	AF2	VCCAUX
VCCAUX	VCCAUX	AB4	VCCAUX
VCCAUX	VCCAUX	AB5	VCCAUX
VCCAUX	VCCAUX	AB11	VCCAUX
VCCAUX	VCCAUX	AB17	VCCAUX
VCCAUX	VCCAUX	AB22	VCCAUX
VCCAUX	VCCAUX	A24	VCCAUX
VCCINT	VCCINT	Y4	VCCINT
VCCINT	VCCINT	Y8	VCCINT
VCCINT	VCCINT	Y11	VCCINT
VCCINT	VCCINT	Y18	VCCINT
VCCINT	VCCINT	Y19	VCCINT
VCCINT	VCCINT	W18	VCCINT

Table 68: **Spartan-3A DSP FG676 Pinout for XC3SD3400A FPGA *(Cont'd)***

Bank	XC3SD3400A Pin Name	FG676 Ball	Type
VCCINT	VCCINT	U12	VCCINT
VCCINT	VCCINT	T11	VCCINT
VCCINT	VCCINT	T13	VCCINT
VCCINT	VCCINT	T15	VCCINT
VCCINT	VCCINT	R12	VCCINT
VCCINT	VCCINT	R14	VCCINT
VCCINT	VCCINT	R16	VCCINT
VCCINT	VCCINT	P11	VCCINT
VCCINT	VCCINT	P13	VCCINT
VCCINT	VCCINT	P14	VCCINT
VCCINT	VCCINT	P15	VCCINT
VCCINT	VCCINT	N12	VCCINT
VCCINT	VCCINT	N13	VCCINT
VCCINT	VCCINT	N14	VCCINT
VCCINT	VCCINT	N16	VCCINT
VCCINT	VCCINT	M11	VCCINT
VCCINT	VCCINT	M13	VCCINT
VCCINT	VCCINT	M15	VCCINT
VCCINT	VCCINT	M17	VCCINT
VCCINT	VCCINT	L12	VCCINT
VCCINT	VCCINT	L14	VCCINT
VCCINT	VCCINT	L16	VCCINT
VCCINT	VCCINT	K15	VCCINT
VCCINT	VCCINT	G18	VCCINT
VCCINT	VCCINT	F10	VCCINT
VCCINT	VCCINT	F18	VCCINT
VCCINT	VCCINT	E6	VCCINT
VCCINT	VCCINT	D5	VCCINT
VCCINT	VCCINT	C4	VCCINT
VCCINT	VCCINT	AA8	VCCINT

User I/Os by Bank

Table 69 indicates how the available user-I/O pins are distributed between the four I/O banks on the FG676 package. The AWAKE pin is counted as a dual-purpose I/O.

Table 69: **User I/Os Per Bank for the XC3SD3400A in the FG676 Package**

Package Edge	I/O Bank	Maximum I/Os and Input-Only	All Possible I/O Pins by Type				
			I/O	INPUT	DUAL	VREF[1]	CLK
Top	0	111	82	11	1	9	8
Right	1	123	67	8	30	10	8
Bottom	2	112	68	6	21	9	8
Left	3	123	97	9	0	9	8
TOTAL		**469**	**314**	**34**	**52**	**37**	**32**

Notes:

1. 26 VREF are on INPUT pins.

Right Half of FG676 Package (Top View)

Figure 17: **FG676 Package Footprint for XC3SD3400A FPGA (Top View–Right Half)**